

TH 935-2 Silicone Thermal Pad

Description

TH 935-2 is a thermally conductive silicone interface pads which designed to provide a better heat-transfer path between heat-generating IC packaging and heat sinks or other cooling devices. It is designed for superior thermal conduction and high electrical insulation. This silicone pad comes with both side non-tacky and can be cut into shapes required.

Applications

1. Thermal conductive interface material for electronic parts and devices.

Properties

Property	Test Method	Unit	Typical Value
Chemical type	-	-	Silicone
Appearance	Pen 10	-	White
Thermal conductivity	ISO/DIS 22007	Wm ⁻¹ K ⁻¹	4.6
Volatile content	-	%	< 1.0
Hardness	Pen 29	Shore A	50
Specific gravity (cured)	Pen 14	-	2.2

Guidelines for Use

1. Wear rubber gloves when handling the silicone pad.
2. Pick up some of the silicone thermal pad from the container using hand.
3. Place the silicone thermal pad in required electronic part and circuit by hand.
4. Not require heating and curing.
5. The thermal pad can be applied and removed easily (care must be taken during installation to avoid tearing).

Storage

Store this silicone thermal pad in air tight container, cool, dark place (temperature range from 20°C to 30°C) to prolong shelf life. Prevent moisture condition.

Packaging & Dimension

- Sheet form
- Will provide customized dimension if required

Environment, Health & Safety

This product is RoHS compliant. It does not contain any known carcinogenic, mutagenic or teratogenic components.

Contact Information

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